**ON Semiconductor** 

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# Onsemí

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# PLL Frequency Synthesizer for Electronic Tuning

#### Overview

The LC72121, LC72121M and LC72121V are high input sensitivity (20 mVrms at 130 MHz) PLL frequency synthesizers for 3 V systems. These ICs are serial data (CCB\*) compatible with the LC72131, and feature the improved input sensitivity and lower spurious radiation (provided by a redesigned ground system) required in high-performance AM/FM tuners.

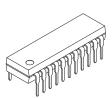
#### Functions

- High-speed programmable divider
  - FMIN: 10 to 160 MHz ... Pulse swallower technique (With built-in divide-by-2 prescaler)
  - AMIN: 2 to 40 MHz ... Pulse swallower technique
     0.5 to 10 MHz ... Direct division technique
- IF counter
- IFIN: 0.4 to 15 MHz ... For AM and FM IF counting
- Reference frequency
  - One of 12 reference frequencies can be selected (using a 4.5 or 7.2 MHz crystal element)
  - 1, 3, 5, 9, 10, 3.125, 6.25, 12.5, 15, 25, 50, and 100 kHz
- Phase comparator
  - Supports dead zone control.
  - Built-in unlocked state detection circuit
  - Built-in deadlock clear circuit
- An MOS transistor for an active low-pass filter is built in
- I/O ports
  - Output-only ports: 4 pins
  - I/O ports: 2 pins
  - Supports the output of a clock time base signal
- Operating ranges
  - Supply voltage: 2.7 to 3.6 V
  - Operating temperature: 40 to 85°C
- Package
  - DIP22S, MFP24S, SSOP24

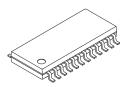
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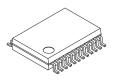
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PDIP22 / DIP22S (300 mil) [LC72121]



SOIC24 W / MFP24S (300 mil) [LC72121M]



SSOP24 (275mil) [LC72121V]

\* Computer Control Bus (CCB) is an ON Semiconductor's original bus format and the bus addresses are controlled by ON Semiconductor.

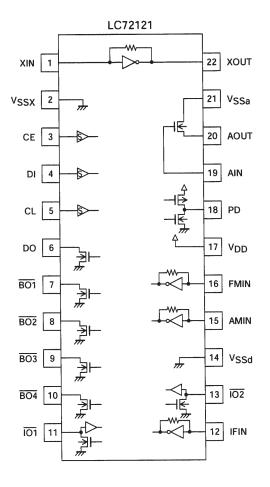
#### **ORDERING INFORMATION**

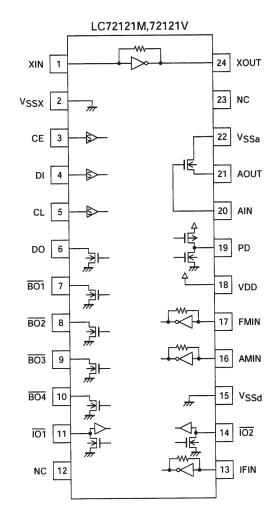
See detailed ordering and shipping information on page 26 of this data sheet.

#### • Comparison with the LC72131/M

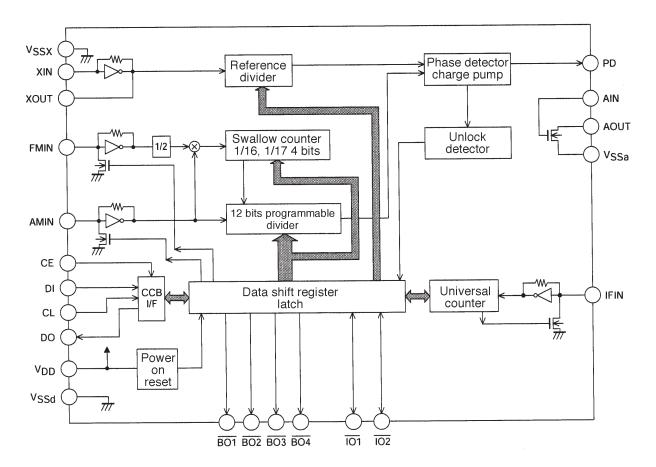
- Serial data compatible (CCB)
- Identical pin functions
- Two VSS pins were added
- The DIP version is pin compatible
- (VSS pins were inserted as the DIP22S NC pins)
- The MFP product provides a modified pin assignment
- (The MFP20 package was replaced by an MFP24 package, and extra VSS pins were added)
- The SSOP24 is a newly developed package that has the same pin assignment as the MFP24S product

#### **Pin Assignment**





#### **Block Diagram**



#### Specifications Absolute Maximum Ratings at Ta = 25°C, V<sub>SSd</sub> = V<sub>SSa</sub>= V<sub>SSX</sub> = 0 V

Parameter	Symbol	Conditions		Ratings	Unit
Maximum supply voltage	V <sub>DD</sub> max	V <sub>DD</sub>		-0.3 to +7.0	V
	V <sub>IN</sub> 1 max	CE, DI, CL, AIN	-0.3 to +7.0	V	
Maximum input voltage	V <sub>IN</sub> 2 max	XIN, FMIN, AMIN, IFIN	-0.3 to V <sub>DD</sub> +0.3	V	
	V <sub>IN</sub> 3 max	ĪO1, ĪO2	-0.3 to +15	V	
	V <sub>O</sub> 1 max	DO	-0.3 to +7.0	V	
Maximum output voltage	V <sub>O</sub> 2 max	XOUT, PD	-0.3 to V <sub>DD</sub> +0.3	V	
	V <sub>O</sub> 3 max	BO1 to BO4, IO1, IO2, AOUT	-0.3 to +15	V	
• • • • •	I <sub>O</sub> 1 max	DO, AOUT	0 to +6.0	mA	
Maximum output current	I <sub>O</sub> 2 max	BO1 to BO4, IO1, IO2		0 to +10.0	mA
			DIP22S:	350	mW
Allowable power dissipation	Pd max	(Ta ≤ 85°C)	MFP24S:	200	mW
			SSOP24:	150	mW
Operating temperature	Topr			-40 to +85	°C
Storage temperature	Tstg			-55 to +125	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### Allowable Operating Ranges at Ta = -40 to $+85^{\circ}$ C, V<sub>SSd</sub> = V<sub>SSa</sub> = V<sub>SSX</sub> = 0 V

Deremeter	Ourseland	Conditions		Ratings		- Unit
Parameter	Symbol	Conditions	min	typ	max	
Supply voltage	V <sub>DD</sub>	V <sub>DD</sub>	2.7		3.6	V
Innut high lovel veltage	V <sub>IH</sub> 1	CE, DI, CL	0.7 V <sub>DD</sub>		6.5	V
Input high-level voltage	V <sub>IH</sub> 2	<u>101, 102</u>	0.7 V <sub>DD</sub>		13	V
Input low-level voltage	V <sub>IL</sub>	CE, DI, CL, IO1, IO2	0		0.3 V <sub>DD</sub>	V
Output veltage	V <sub>O</sub> 1	DO	0		6.5	V
Output voltage	V <sub>O</sub> 2	BO1 to BO4, IO1, IO2, AOUT	0		13	V
	f <sub>IN</sub> 1	XIN: V <sub>IN</sub> 1	1		8	MHz
	f <sub>IN</sub> 2	FMIN: V <sub>IN</sub> 2	10		160	MHz
Input frequency	f <sub>IN</sub> 3	AMIN (SNS = 1): V <sub>IN</sub> 3	2		40	MHz
	f <sub>IN</sub> 4	AMIN (SNS = 0): $V_{IN}4$	0.5		10	MHz
	f <sub>IN</sub> 5	IFIN: V <sub>IN</sub> 5	0.4		15	MHz
	V <sub>IN</sub> 1	XIN: f <sub>IN</sub> 1	200		800	mVrms
	V <sub>IN</sub> 2-1	FMIN: f = 10 to 130 MHz	20		800	mVrms
	V <sub>IN</sub> 2-2	FMIN: f = 130 to 160 MHz	40		800	mVrms
Input amplitude	V <sub>IN</sub> 3	AMIN (SNS = 1): f <sub>IN</sub> 3	40		800	mVrms
	V <sub>IN</sub> 4	AMIN (SNS = 0): f <sub>IN</sub> 4	40		800	mVrms
	V <sub>IN</sub> 5-1	IFIN: f <sub>IN</sub> 5, IFS = 1	40		800	mVrms
	V <sub>IN</sub> 5-2	IFIN: f <sub>IN</sub> 5, IFS = 0	70		800	mVrms
Guaranteed crystal oscillator frequency	Xtal	XIN, XOUT: *	4		8	MHz

Note: Recommended value for CI for the crystal oscillator element: CI  $\leq$  120 $\Omega$  (4.5MHz), CI  $\leq$  70 $\Omega$  (7.2MHz)

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

#### Electrical Characteristics in the Allowable Operating Ranges

Parameter	Cumbal	Conditions	Ratings			Unit	
Parameter	Symbol	Conditions	min	typ	max	Unit	
	Rf1	XIN		1		MΩ	
Internal feedback resistance	Rf2	FMIN		500		kΩ	
	Rf3	AMIN		500		kΩ	
	Rf4	IFIN		250		kΩ	
Internal pull-down resistance	Rpd1	FMIN	100	200	400	kΩ	
	Rpd2	AMIN	100	200	400	kΩ	
Hysteresis	V <sub>HIS</sub>	CE, DI, CL		0.1 V <sub>DD</sub>		V	
Output high-level voltage	V <sub>OH</sub> 1	PD: I <sub>O</sub> = -1 mA	V <sub>DD</sub> – 1.0			V	

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Parameter	Symbol	Conditions		Ratings		Unit
Falameter	Symbol	Conditions	min	typ	max	
	V <sub>OL</sub> 1	PD: I <sub>O</sub> = 1 mA			1.0	V
		$\overline{\text{BO1}}$ to $\overline{\text{BO4}}$ , $\overline{\text{IO1}}$ , $\overline{\text{IO2}}$ : I <sub>O</sub> = 1 mA			0.2	V
Output low-level voltage	V <sub>OL</sub> 2	$\overline{\text{BO1}}$ to $\overline{\text{BO4}}$ , $\overline{\text{IO1}}$ , $\overline{\text{IO2}}$ : I <sub>O</sub> = 8 mA			1.6	V
		DO: I <sub>O</sub> = 1 mA			0.2	V
	V <sub>OL</sub> 3	DO: I <sub>O</sub> = 5 mA			1.0	V
	V <sub>OL</sub> 4	AOUT: I <sub>O</sub> = 1 mA, AIN = 1.3 V			0.5	V
	I <sub>IH</sub> 1	CE, DI, CL: V <sub>I</sub> = 6.5 V			5.0	μA
	I <sub>IH</sub> 2	<u>IO1</u> , <u>IO2</u> : V <sub>I</sub> = 13 V			5.0	μA
Innut bird lovel ourrest	I <sub>IH</sub> 3	$XIN: V_1 = V_{DD}$	1.3		8	μA
Input high-level current	I <sub>IH</sub> 4	FMIN, AMIN: V <sub>I</sub> = V <sub>DD</sub>	2.5		15	μA
	I <sub>IH</sub> 5	IFIN: VI = VDD	5.0		30	μA
	I <sub>IH</sub> 6	AIN: V <sub>1</sub> = 6.5 V			200	nA
	I <sub>IL</sub> 1	CE, DI, CL: VI = 0 V			5.0	μA
	I <sub>IL</sub> 2	$\overline{IO1}, \overline{IO2}: V_I = 0 V$			5.0	μA
Input low-level current	I <sub>IL</sub> 3	$XIN: V_1 = 0 V$	1.3		8	μA
Input low-level current	I <sub>IL</sub> 4	FMIN, AMIN: $V_1 = 0 V$	2.5		15	μA
	I <sub>IL</sub> 5	IFIN: VI = 0 V	5.0		30	μA
	I <sub>IL</sub> 6	AIN: $V_1 = 0 V$			200	nA
Output off leakage current	I <sub>OFF</sub> 1	$\overline{\text{BO1}}$ to $\overline{\text{BO4}}$ , $\overline{\text{IO1}}$ , $\overline{\text{IO2}}$ , AOUT: V <sub>O</sub> = 13 V			5.0	μA
Output on leakage current	I <sub>OFF</sub> 2	DO: V <sub>O</sub> = 6.5 V			5.0	μA
High-level 3-state off leakage current	I <sub>OFFH</sub>	PD: $V_0 = V_{DD}$		0.01	200	nA
Low-level 3-state off leakage current	IOFFL	PD: $V_0 = 0 V$		0.01	200	nA
Input capacitance	C <sub>IN</sub>	FMIN		6		pF
	I <sub>DD</sub> 1	$V_{DD}$ : Xtal = 7.2 MHz, f <sub>IN</sub> 2 = 130 MHz, $V_{IN}2$ = 20 mVrms		2.5	6	mA
Supply current	I <sub>DD</sub> 2	V <sub>DD</sub> : PLL block stopped (PLL inhibit mode) Crystal oscillator operating (crystal frequency: 7.2 MHz)		0.3		mA
	I <sub>DD</sub> 3	V <sub>DD</sub> : PLL block stopped, crystal oscillator stopped			10	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### **Pin Descriptions**

Pin	Pin I	No.	Turne	Function	
name	LC72121	LC72121M LC72121V	Туре	Function	Equivalent circuit
XIN XOUT	1 22	1 24	Xtal	Crystal oscillator element connections (4.5 or 7.2 MHz)	A10146
				<ul> <li>FMIN is selected when DVS in the serial data is set to 1.</li> </ul>	
				Input frequency: 10 to 160 MHz	
FMIN	16	17	oscillator	• The signal is passed through an internal divide-by-two prescaler and then input to the swallow counter.	
				• The divisor can be set to a value in the range 272 to 65535. Since the internal divide-by-two prescaler is used, the actual divisor will be twice the set value.	7/7 A10147
				AMIN is selected when DVS in the serial data is set to 0.	
				When SNS in the serial data is set to 1:	
				Input frequency: 2 to 40 MHz	
				<ul> <li>The signal is input to the swallow counter directly.</li> </ul>	
AMIN	15	16	Local oscillator	• The divisor can be set to a value in the range 272 to 65535. The set value becomes the actual divisor.	
			signal input	When SNS in the serial data is set to 0:	<u> </u>
				Input frequency: 0.5 to 10 MHz	
				<ul> <li>The signal is input to a 12-bit programmable divider directly.</li> </ul>	A10148
				• The divisor can be set to a value in the range 4 to 4095. The set value becomes the actual divisor.	

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Pin	Pin I	No.	-		
name	LC72121	LC72121M LC72121V	Туре	Function	Equivalent circuit
CE	3	3	Chip enable	<ul> <li>This pin must be set high to enable serial data input (DI) or serial data output (DO).</li> </ul>	A10149
DI	4	4	Input data	Input for serial data transferred from the controller	A10150
CL	5	5	Clock	<ul> <li>Clock used for data synchronization for serial data input (DI) and serial data output (DO).</li> </ul>	□\$>>> A10151
DO	6	6	Output data	<ul> <li>Output for serial data transmitted to the controller. The content of the data transmitted is determined by DOC0 through DOC2.</li> </ul>	
V <sub>DD</sub>	17	18	Power supply	LC72121 power supply (V <sub>DD</sub> 2.7 to 3.6 V)     The power on reset circuit operates when power is first applied.	
V <sub>SSX</sub>	2	2	Ground	Ground for the crystal oscillator circuit	
V <sub>SSA</sub>	21	22	Ground	Ground for the low-pass filter MOS transistor	
				Ground for the LC72121 digital systems other than those that use	
V <sub>SSd</sub>	14	15	Ground	$V_{SSa}$ or $V_{SSX}$ .	
101 102	11 13	11 14	I/O port	<ul> <li>Shared function I/O ports</li> <li>The pin function is determined by IOC1 and IOC2 in the serial data. When the data value 0: Input port</li> <li>When the data value 1: Output port</li> <li>When specified to function as an input port: The input pin state is reported to the controller through the DO pin. When the input state is low: The data will be 0: When the input state is low: The data will be 1:</li> <li>When specified to function as an output port: The output state is determined by IO1 and IO2 in the serial data. When the data value is 0: The output state will be the open circuit state. When the data value is 1: The output state will be a low level.</li> <li>These pins are set to input mode after a power on reset.</li> </ul>	A10153
BO1 BO2 BO3 BO4	7 8 9 10	7 8 9 10	Output port	<ul> <li>Output-only ports</li> <li>The output state is determined by BO1 through BO4 in the serial data.</li> <li>When the data value is 0: The output state will be the open circuit state.</li> <li>When the data value is 1: The output state will be a low level.</li> <li>A time base signal (8 Hz) is output from BO1 when TBC in the serial data is set to 1.</li> </ul>	
PD	18	19	Charge pump output	<ul> <li>PLL charge pump output         A high level is output when the frequency of the local oscillator signal divided by N is higher than the reference frequency, and a low level is output when that frequency is lower. This pin goes to the high-impedance state when the frequencies match.     </li> </ul>	A10155
AIN AOUT	19 20	20 21	Low-pass filter amplifier transistor	Connections for the MOS transistor used for the PLL active low-pass filter.	
IFIN	12	13	IF counter	<ul> <li>The input frequency range is 0.4 to 15 MHz</li> <li>The signal is passed directly to the IF counter.</li> <li>The result is output, MSB first, through the DO pin.</li> <li>Four measurement periods are supported: 4, 8, 32, and 64 ms.</li> </ul>	A10157
NC		12 23	NC pin	No connection	

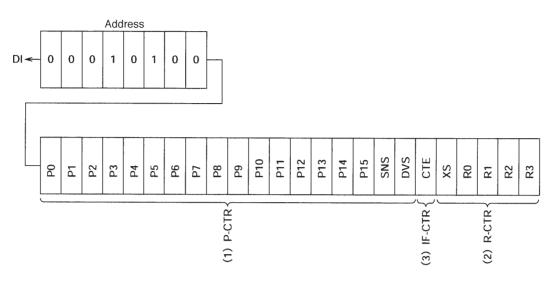
## Procedures for Input and Output of Serial Data

This product uses the CCB (Computer Control Bus), which is original audio product serial bus format, for data input and output. This product adopts an 8-bit address CCB format.

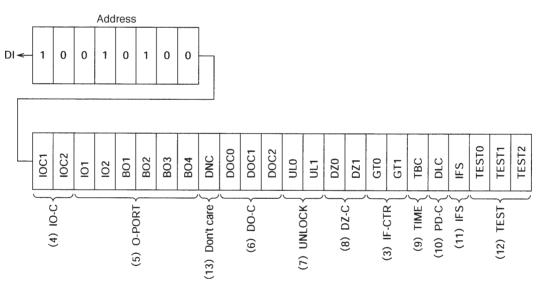
$\square$	1/O mada				Add	lress				Eurofian						
	I/O mode	B0	B1	B2	B3	A0	A1	A2	A3	Function						
1	IN1 (82)	0	0	0	1	0	1	0	0	<ul> <li>Control data input (serial data input) mode</li> <li>24 bits of data are input.</li> <li>See the "DI Control Data (serial data input)" section for details on the content of the input data.</li> </ul>						
2	IN2 (92)	1	0	0	1	0	1	0	0	<ul> <li>Control data input (serial data input) mode</li> <li>24 bits of data are input.</li> <li>See the "DI Control Data (serial data input)" section for details on the content of the input data.</li> </ul>						
3	OUT (A2)	0	1	0	1	0	1	0	0	<ul> <li>Data output (serial data output) mode</li> <li>The number of bits output is equal to the number of clock cycles.</li> <li>See the "DO output Data (serial data output)" section for details on the content of the output data.</li> </ul>						
C	@	<u></u> Во			B2	B3		) <b>X</b> ,		I/O mode determined         I/O mode determin						

Structure of the DI Control Data (serial data input)

• IN1 mode



• IN2 mode



A10160

#### **DI Control Data**

No.	Control block/data							F	unction			Related data
		•	Spec	ifies th	ne div	isor fo	or the progra	ammable divide	:			
		•	This i	is a bir	nary v	alue i	in which P1	5 is the MSB. T	ne LSB change	es depending or	DVS and SNS.	
									(* : do	on't care)		
			D	VS	SI	NS	LSB	Set divisor (N	) Actual d	livisor		
				1		*	P0	272 to 65535	Twice the s	set value		
				0		1	P0	272 to 65535	The set	value		
				0		0	P4	4 to 4095	The set	value		
	Programmable divider data	*	I SB-	When	P4 is	the l	SB P0 to I	P3 are ignored.				
1	P0 to P15	'	LOD.	which	11 4 10		-00,10101	o are ignored.				
'	DVS, SNS						signal input	to the program	mable divider (I	FMIN or AMIN)	and switch the input	
		1	frequ	ency r	ange.							
										(* : don't care)		
			D	VS	SI	NS	Input pin	Frequency rar	ge accepted b	y the input pin		
				1		*	FMIN		10 to 160 MHz			
				0		1	AMIN		2 to 40 MHz			
				0		0	AMIN		0.5 to 10 MHz			
		* 9	See t	he "St	ructu	re of t	he Program	mable Divider"	section for deta	aile		
		`			luciu		ne i rogran					
		•	Refer	ence	freque	ency s	selection					
			R3	R2	R1	R0	Re	ference frequen	CV.			
			0	0	0	0	1.0	100 kHz	-			
			0	0	0	1		50				
			0	0	1	0		25				
			0	0	1	1		25				
				12.5								
			0	1	0	1		6.25				
			0	1	1	0		3.125				
			0	1	1	1		3.125				
	Reference divider		1	0	0	0		10				
	data		1	0	0	1		9				
2	R0 to R3		1	0	1	0		5				
	XS		1	0	1	1		1				
			1	1	0	0		3				
			1	1	0	1		15				
			1	1	1	0		IIBIT + Xtal OSC	, 510P			
				1								
		1		NHIBI								
											ne FMIN, AMIN, and IFIN mpedance state.	
		1					ent selectio		ump output goe		npedance state.	
				0: 4.5			ent selectio	ii dala				
				1: 7.2								
		N	ote th	at 7.2	MHz	is sel	ected after	a power on rese	et.			
		$\vdash$										
		1						nmand data				
				= 1: S = 0: P			ounter					
								rement time.				
	IF counter control	`'								1		
3	data			ST1		Т0		ment time	Wait time	-		IFS
	CTE		<u> </u>	0		0		ms	3 to 4 ms	-		
	GT0, GT1			0		1		8	3 to 4	-		
		1										
				1		0 1		32 54	7 to 8 7 to 8			

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No.	Control block/data				Function		Related data
4	I/O port setup data IOC1,IOC2	Data = 0: I		out for the shared	function I/O pins ( $\overline{IO1}$ and $\overline{IO2}$ ).		
5	Output port data BO1 to BO4 IO1,IO2	Data = 0: 0 Data = 1: L	Dpen ₋ow level		I through $\overline{BO4}$ , $\overline{IO1}$ , and $\overline{IO2}$ output to the open state, after a power on		IOC1 IOC2
		Determine	s the DO pi	n output.			
		DOC2	DOC1	DOC0	DO pin state	]	
		0	0	0	Open		
		0	0	1 Lo	w when the PLL is unlocked		
		0	1	0	end-UC *1		
		0	1	1	Open		
		1	0	0	Open		
		1	0	1	The IO1 pin state *2		
		1	1	0	The IO2 pin state *2		
		1	1	1	Open		
	DO pin control data	The open sta	ate is select	ed after a power	on reset.	-	UL0, UL1
	DO pill control data	*1. end-UC:	IF counter	measurement en	d check		CTE
6	DOC1		_		)		
	DOC2		DO pin	$\{\mathcal{N}}$	``` <u>¥</u> >		IOC1
	2002			(1) Count start	(2) Count end (	i DCE: bigh	IOC2
				U Count start	<ol> <li>Count end</li> </ol>	3)CE: high A10161	
		automatica (2)When the application (3)The DO p pin is set h *2. The DO Note: During open s period synchr	ally goes to IF counter is to test for in is set to f igh). pin will go to the data in state regard that CE is I conization w	the open state. measurement per the completion of the open state by the open state by the open state i put period (the p less of the DO pi nigh in OUT mod with the CL clock,	ount is started (by switching CTE f period completes, the DO pin goes to of the count period. If performing a serial data input or c if the corresponding IO pin is set up eriod that CE is high in IN1 or IN2 n control data (DOC0 to DOC2). D e) the DO pin state reflects the inter regardless of the DO pin control data	o the low level, allowing output operation (when the CE o to be an output port. mode), the DO pin goes to the uring the data output period (the ernal DO serial data in ata (DOC0 to DOC2).	
					E) detected for PLL lock state discr of the detection width occurs.	imination. The state is taken to	
	Unlocked state		010	Stopped	Open		DOC0
7	detection data	0	1	0	øE is output directly		DOC1
	UL0, UL1		0	±0.55 µs	øE is extended by 1 to 2	ms	DOC2
		1	1	±1.11 µs	øE is extended by 1 to 2		
				-	goes low and UL in the serial data		
				, ,			
		Controis tr	ie priase co	mparator dead z			
		DZ1	DZ	Dead zone m	ode		
	1	0	0	DZA			
	Phase comparator						
8	control data	0	1	DZB			
8		0	1 0	DZB DZC			
8	control data						

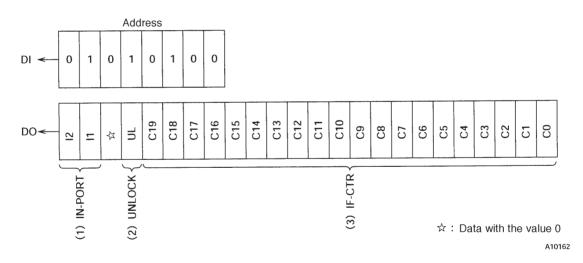
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No.	Control block/data	Function	Related data
9	Clock time base TBC	• Setting the TBC bit to 1 causes an 8-Hz clock time base signal with a 40% duty to be output from the $\overline{\text{BO1}}$ pin. (The BO1 data will be ignored.)	BO1
10	Charge pump control data DLC	Forcibly controls the charge pump output.     DLC Charge pump output     0 Normal operation     1 Forced to low      If the circuit deadlocks due to the VCO control voltage (Vtune) being 0 and the VCO being stopped,     applications can get out of the deadlocked state by setting the charge pump output to low and setting     Vtune to V <sub>CC</sub> . (Deadlock clear circuit)	
11	IF counter control data IFS	<ul> <li>This data is normally set to 1. Setting this data to 0 sets the circuit to reduced input sensitivity mode, in which the sensitivity is reduced by about 10 to 30 mV rms.</li> <li>* See the "IF Counter Operation" section for details.</li> </ul>	
12	Test data TEST0 to 2	Test data     TEST0     TEST1     All these bits must be set to 0.     TEST2     All these bits are set to 0 after a power on reset.	
13	DNC	This bit must be set to 0.	

#### Structure of the DO Output Data (serial data output)

• OUT mode

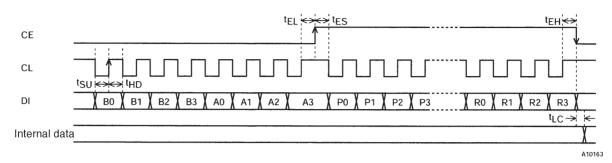


#### DO Output Data

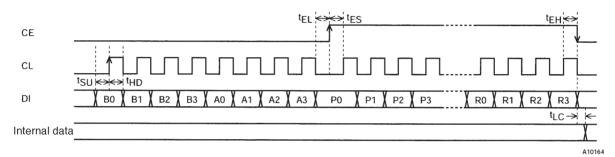
No.	Control block/data	Function	Related data
1	I/O port data 12, I1	<ul> <li>Data latched from the I/O port IO1 or IO2 pin states.</li> <li>These bits reflect the pin states regardless of the I/O port mode (input or output). The data is latched at the point the circuit enters data output mode (OUT mode). I1 ← The IO1 pin state I2 ← The IO2 pin state L:0</li> </ul>	IOC1 IOC2
2	PLL unlocked state data UL	<ul> <li>Indicates the state of the unlocked state detection circuit.</li> <li>UL ← 0: When the PLL is unlocked.</li> <li>UL ← 1: When the PLL is locked or in the detection disabled mode.</li> </ul>	UL0 UL1
3	IF counter binary data C19 to C0	<ul> <li>Indicates the value of the IF counter (20-bit binary counter).</li> <li>C19 ← MSB of the binary counter</li> <li>C0 ← LSB of the binary counter</li> </ul>	CTE GT0 GT1

#### Serial Data Input (IN1/IN2) $t_{SU},\,t_{HD},\,t_{EL},\,t_{ES},\,t_{EH} \geq 0.75~\mu s~t_{LC}$ < 0.75 $\mu s$

• CL: Normally high

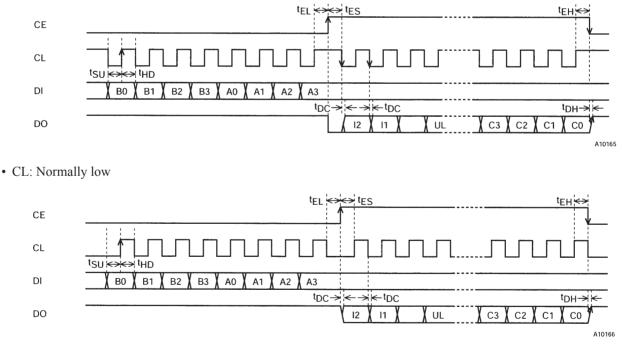


#### • CL: Normally low



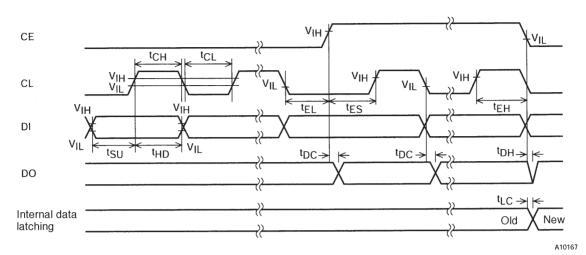
#### Serial Data Output (Out) $t_{SU},\,t_{HD},\,t_{EL},\,t_{ES},\,t_{EH} \geq 0.75~\mu s~t_{DC},\,t_{DH}$ < 0.35 $\mu s$

• CL: Normally high

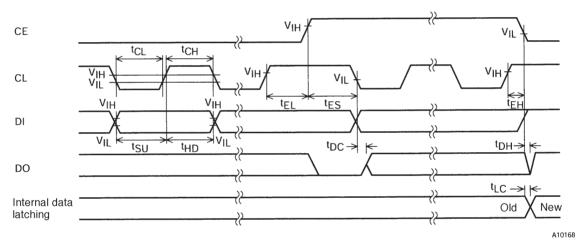


Note: The data conversion times (t<sub>DC</sub> and t<sub>DH</sub>) depend on the value of the pull-up resistor and the printed circuit board capacitance since the DO pin is an n-channel open-drain circuit.

#### Serial Data Timing



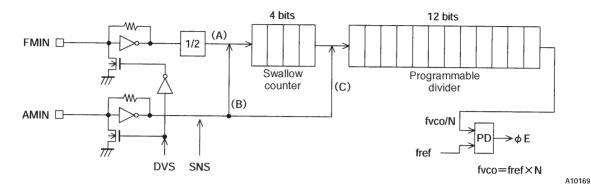
When CL is Stopped at the Low Level



When CL is Stopped at the High Level

Parameter	Cumbal		Conditions			1 lait	
Parameter	Symbol		Conditions	min	typ	max	Unit
Data setup time	t <sub>SU</sub>	DI, CL		0.75			μs
Data hold time	t <sub>HD</sub>	DI, CL		0.75			μs
Clock low level time	t <sub>CL</sub>	CL		0.75			μs
Clock high level time	t <sub>CH</sub>	CL		0.75			μs
CE wait time	t <sub>EL</sub>	CE, CL		0.75			μs
CE setup time	t <sub>ES</sub>	CE, CL		0.75			μs
CE hold time	t <sub>EH</sub>	CE, CL		0.75			μs
Data latch change time	t <sub>LC</sub>					0.75	μs
Data output time	t <sub>DC</sub>	DO, CL	These values differ depending on the value of the pull-up			0.35	μs
Data output time	t <sub>DH</sub>	DO, CE	resistor used and the printed circuit board capacitance.			0.35	μs

#### Structure of the Programmable Divider



DVS SNS Input pin Set divisor Actual divisor Input frequency range А \* FMIN 272 to 65535 Twice the set value 10 to 160 MHz 1 В 272 to 65535 2 to 40 MHz 0 1 AMIN The set value С AMIN 4 to 4095 0.5 to 10 MHz 0 The set value 0

\*: Don't care

#### Sample Programmable Divider Divisor Calculations

- For FM with a step size of 50 kHz (DVS = 1, SNS = \*: FMIN selected)
  - FM RF = 90.0 MHz (IF +10.7 MHz)

FM VCO = 100.7 MHz

PLL fref = 
$$25 \text{ kHz}$$
 (R0 = 0, R1 = 1, R2 = 0, R3 = 0)

100.7 MHz (FM VCO)  $\div$  25 kHz (fref)  $\div$  2 (for the FMIN 1/2 prescaler) 2014  $\rightarrow$  07DE (hexadecimal)

						)				1				)									
0	1	1	1	1	0	1	1	1	1	1	0	0	0	0	0	*	1			0	1	0	0
PO	P	P2	P3	P4	P5	Ъ6	P7	P8	6d	P10	P11	P12	P13	P14	P15	SNS	DVS	CTE	XS	R0	R1	R2	R3

• For SW with a step size of 5 kHz (DVS = 0, SNS = 1: AMIN high-speed operation selected) SW RF = 21.75 MHz (IF +450 kHz)

SW VCO = 22.20 MHz

PLL fref = 5 kHz (R0 = 0, R1 = 1, R2 = 0, R3 = 1)

22.2 MHz (SW VCO)  $\div$  5 kHz (fref) = 4440  $\rightarrow$  1158 (hexadecimal)

		}			5	5							1										
0	0	0	1	1	0	1	0	1	0	0	0	1	0	0	0	1	0			0	1	0	1
PO	P1	P2	P3	P4	P5	9d	P7	P8	6d	P10	P11	P12	P13	P14	P15	SNS	DVS	CTE	XS	R0	R1	R2	R3

• For MW with a step size of 9 kHz (DVS = 0, SNS = 0: AMIN low-speed operation selected) MW RF = 1008 kHz (IF +450 kHz)

WM VCO = 1458 kHz

PLL fref =9 kHz (R0 = 1, R1 = 0, R2 = 0, R3 = 1)

1458 (MW VCO)  $\div$  9 kHz (fref) = 162  $\rightarrow$  0A2 (hexadecimal)

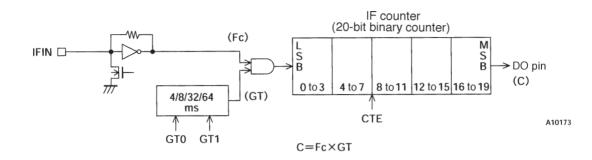
										4			(	)									
*	*	*	*	0	1	0	0	0	1	0	1	0	0	0	0	0	0			1	0	0	1
Dd	P1	P2	P3	P4	P5	96	P7	P8	6d	P10	P11	P12	P13	P14	P15	SNS	DVS	CTE	XS	R0	R1	R2	R3

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#### Structure of the IF Counter

The LC72121 IF counter is a 20-bit binary counter, and takes the IF signal from the IFIN pin as its input. The result of the count can be read out serially, MSB first, from the DO pin.



GT1	GT0	Measuren	nent time
GII	610	Measurement time (GT)	Wait time (t <sub>WU</sub> )
0	0	4 ms	3 to 4 ms
0	1	8	3 to 4 ms
1	0	32	7 to 8 ms
1	1	64	7 to 8 ms

The IF frequency (Fc) is measured by determining how many pulses were input to the IF counter in the stipulated measurement time, GT.

 $Fc = \frac{C}{GT} (C = Fc \times GT)$ 

C: Counted value (the number of pulses)

#### **IF Counter Frequency Measurement Examples**

• When the measurement time (GT) is 32 ms and the counted value (C) is 53980 (hexadecimal) or 342,400 (decimal). IF frequency ( $F_C$ ) = 342400 ÷ 32 ms = 10.7 MHz

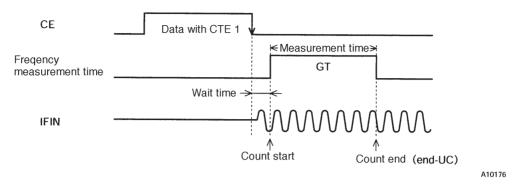
				5	5			;	3				2				3					
			0	1	0	1	0	0	1	1	1	0	0	1	1	0	0	0	0	0	0	0
12	11	٦	C19	C18	C17	C16	C15	C14	C13	C12	C11	C10	C9	C8	C7	C6	C5	C4	C	C2	C	CO

A10174

• When the measurement time (GT) is 8 ms and the counted value (C) is E10 (hexadecimal) or 3600 (decimal). IF frequency ( $F_C$ ) = 3600 ÷ 8 ms = 450 kHz

					)				)			E				1					)	
			0	0	0	0	0	0	0	0	1	1	1	0	0	0	0	1	0	0	0	0
12	5	Ы	C19	C18	C17	C16	C15	C14	C13	C12	C11	C10	C9	C8	C7	C6	C5	C4	C	C2	CI	S

#### IF Counter Operation



Applications must first, before starting an IF count operation reset the IF counter by setting CTE in the serial data to 0. The IF counter operation is started setting CTE in the serial data from 0 to 1. Although the serial data is latched by dropping the CE pin from high to low, the IF signal input to the IFIN pin must be provided within the wait time from the point CE goes low. Next, the readout of the IF counter after measurement is complete must be performed while CTE is still 1, since the counter will be reset if CTE is set to 0.

Note: If IF counting is used, applications must determine whether or not the IF IC SD (station detect) signal is present in the microcontroller software, and perform the IF count only if that signal is asserted. This is because auto-search techniques that use IF counting only are subject to incorrect stopping at points where there is no station due to IF buffer leakage.

Note that the LC72121 input sensitivity can be controlled with the IFS bit in the serial data.

Reduced sensitivity mode (IFS = 0) must be selected when this IC is used in conjunction with an IF IC that does not provide an SD output and auto-search is implemented using only IF counting.

			Input frequency : f [MHz]
IFS data	0.4 ≤ f < 0.5	0.5 ≤ f < 8	$8 \le f \le 15$
1(Normal mode)	40 mVrms (0.1 to 3 mVrms)	40 mVrms	40 mVrms (1 to 15 mVrms)
0 (Degraded sensitivity mode)	70 mVrms (5 to 10 mVrms)	70 mVrms	70 Vrms (30 to 40 mVrms)

IFIN Minimum Sensitivity Standard

Note: Values in parentheses are actual performance values that are provided for reference purposes

#### **Unlocked State Detection Timing**

• Unlocked state detection timing

Unlocked state detection is performed during the reference frequency (fref) period (interval). This means that a period at least as long as the period of the reference frequency is required to recognize the locked/unlocked state. However, applications must wait at least twice the period of the reference frequency immediately after changing the divisor (N) before checking the locked/unlocked state.

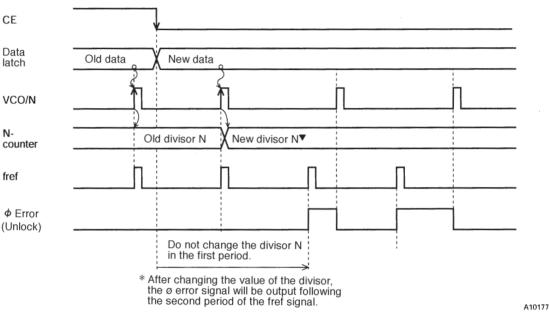
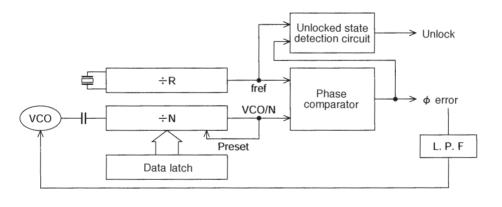
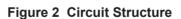


Figure 1 Unlocked State Detection Timing

For example, if fref is 1 kHz (a period of 1 ms) applications must wait at least 2 ms after the divisor N is changed before performing a locked/unlocked check.





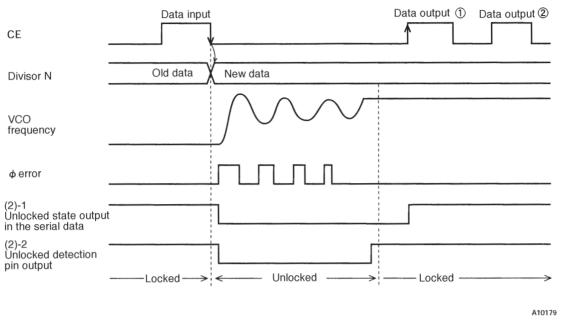
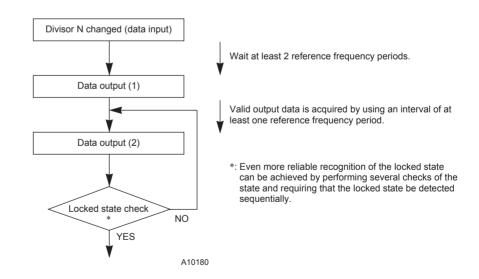


Figure 3 Combining with Software

• Outputting the unlocked state data in the serial data

At the point of data output 1 in figure 3, the unlocked state data will indicate the unlocked state, since the VCO frequency is not stable (locked) yet. In cases such as this, the application should wait at least one whole period and then check again whether or not the frequency has stabilized with the data output 2 operation in the figure. Applications can implement even more reliable recognition of the locked state by performing several more checks of the state and requiring that the locked state be detected sequentially.

<Flowchart for Lock Detection>

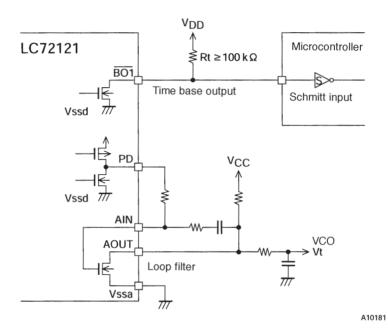


• Directly outputting the unlocked state to the DO pin

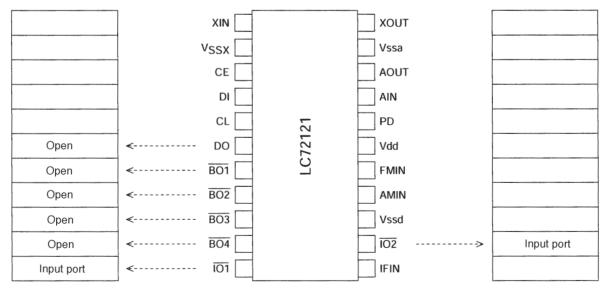
Since the unlocked state (high level when locked, low when unlocked) is output from the DO pin, applications can check for the locked state by waiting at least two reference frequency periods after changing the divisor N. However, in this case also, even more reliable recognition of the locked state can be achieved by performing several checks of the state and requiring that the locked state be detected sequentially.

#### **Clock Time Base Usage Notes**

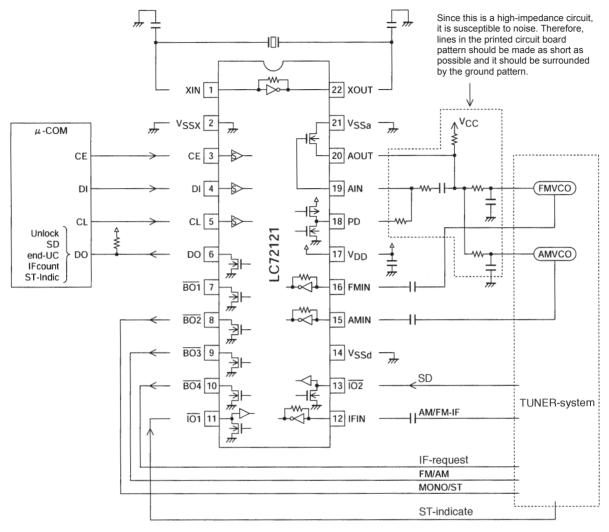
When using the clock time base output function, the output pin  $(\overline{BO1})$  pull-up resistor must have a value of over 100 k $\Omega$ . The use of a Schmitt input in the microcontroller that accepts this signal is recommended to reduce chattering. This is to prevent degradation of the VCO C/N characteristics when combining with a loop filter that uses the internal transistor provided to form a low-pass filter. Although the ground for the clock time base output pin (V<sub>SSd</sub>) and the ground for the transistor (V<sub>SSa</sub>) are isolated internally on the chip, applications must take care to avoid ground loops and minimize current fluctuations in the time base pin to prevent degradation of the low-pass filter characteristics.



#### Pin States after a Power on Reset



# Sample Application Circuit (Using the DIP22S package)



Other Items

DZ1	DZ0	Dead zone mode	Charge pump	Dead zone
0	0	DZA	ON/ON	— —0s
0	1	DZB	ON/ON	-0s
1	0	DZC	OFF/OFF	+0s
1	1	DZD	OFF/OFF	+ +0s

· Notes on the phase comparator dead zone

When the charge pump is used with one of the ON/ON modes, correction pulses are generated from the charge pump even if the PLL is locked. As a result, it is easy for the loop to become unstable, and special care is required in application design. The following problems can occur if an ON/ON mode is used.

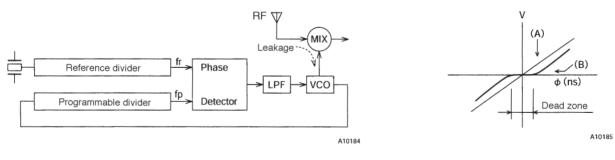
- Sidebands may be created by reference frequency leakage.

- Sidebands may be created by low-frequency leakage due to the correction pulse envelope.

Although the loop is more stable when a dead zone is present (i.e. when an OFF/OFF mode is used), a dead zone makes it more difficult to achieve excellent C/N characteristics. On the other hand, while it is easy to achieve good C/N characteristics when there is no dead zone, achieving good loop stability is difficult. Accordingly, the DZA and DZB settings, in which there is no dead zone, can be effective in situations where a signal-to-noise ratio of 90 to 100 dB or higher is required in FM reception, or where it is desirable to increase the pilot margin in AM stereo reception. However, if such a high signal-to-noise ratio is not required for FM reception, if an adequate pilot margin can be acquired in AM stereo reception, or if AM stereo is not required, then either DZC or DZD, in which there is a dead zone, should be chosen.

#### Dead Zone

As shown in figure 1, the phase comparator compares a reference frequency (fr) with fp. As shown in figure 2, the phase comparator's characteristics consist of an output voltage (V) that is proportional to the phase difference ø. However, due to internal circuit delay and other factors, an actual circuit has a region (the dead zone, B) where the circuit cannot actually compare the phases. To implement a receiver with a high S/N ratio, it is desirable that this region be as small as possible. However, it is often desirable to have the dead zone be slightly wider in popularly-priced models. This is because in certain cases, such as when there is a strong RF input, popularly-priced models can suffer from mixer to VCO RF leakage that modulates the VCO. When the dead zone is small, the circuit outputs signals to correct this modulation and this output further modulates the VCO. This further modulation may then generate beats and the RF signal.



#### Figure 1

Figure 2

Notes on the FMIN, AMIN, and IFIN pins
 Coupling capacitors should be placed as close to their pin as possible. A capacitance of about 100 pF is desirable for
 these capacitors. In particular, if the IFIN pin coupling capacitor is not held under 1000 pF, the time to reach the bias
 level may become excessive and incorrect counts may result due to the relationship with the wait time.

• Notes on IF counting  $\rightarrow$  Use the SD signal in conjunction with IF counting

When counting the IF frequency, the microcontroller must determine the presence or absence of the IF IC SD (station detect) signal and turn on the IF counter buffer output and execute the IF count only if there is an SD signal. Autosearch techniques that only use the IF counter are subject to incorrect stopping at points where there is no station due to IF buffer leakage. • DO pin usage

The DO pin can be used for IF counter count completion checking and as an unlock detection output in addition to its use in data output mode. It is also possible to have the DO pin reflect the state of an input pin to input that state to the microcontroller.

• Power supply pins

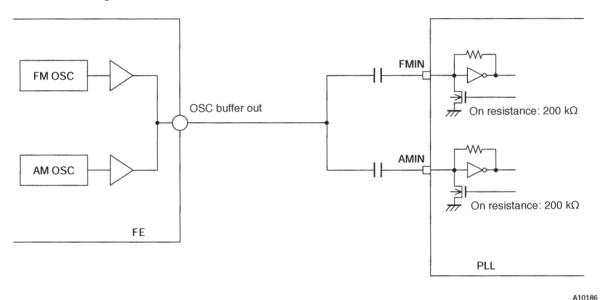
Capacitors must be inserted between the power supply  $V_{DD}$  and  $V_{SS}$  pins for noise exclusion. These capacitors must be placed as close as possible to the  $V_{DD}$  and  $V_{SS}$  pins.

• VCO setup

Applications must be designed so that the VCO (local oscillator) does not stop, even if the control voltage (Vtune) goes to 0 V. If it is possible for the oscillator to stop, the application must use the control data (DLC) to temporarily force Vtune to  $V_{CC}$  to prevent deadlock from occurring. (Deadlock clear circuit)

• Front end connection example

Since this product (and the LC72131 as well) is designed with the relatively high resistance of 200 k $\Omega$  for the pulldown (on) resistors built in to the FMIN and AMIN pins, a common AM/FM local oscillator buffer can be used as shown in the following circuit.



#### • PD pin

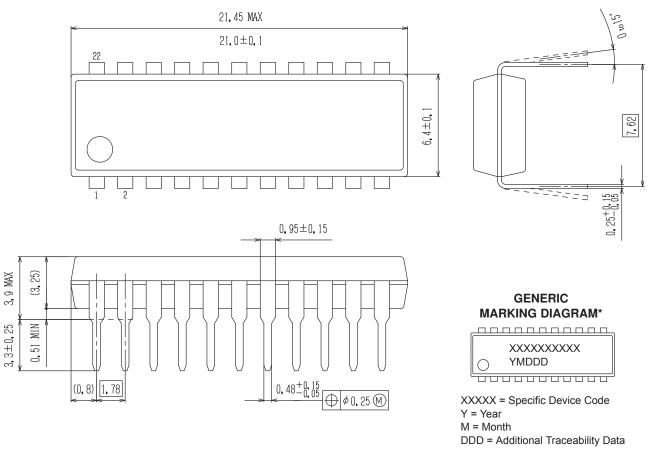
Note that the charge pump output voltage is reduced when this IC, which is a 3-V system, is used to replace the LC72131, which is a 5-V system. This means that since the loop gain is reduced, the loop filter constants, the lock time (SD wait time), and other related parameters must be reevaluated in the end product design.

#### **Package Dimensions**

unit : mm

[LC72121]

#### PDIP22 / DIP22S (300 mil) CASE 646AV ISSUE A



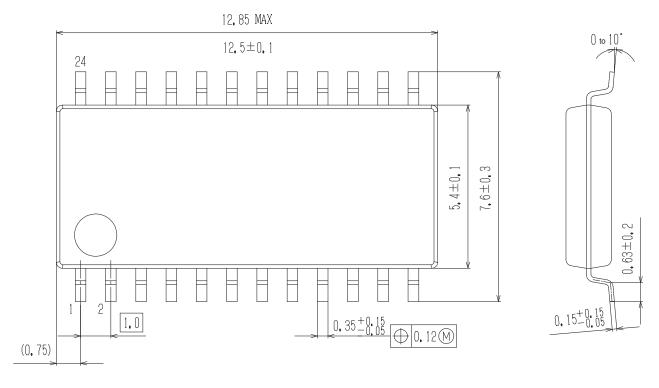
\*This information is generic. Pb-Free indicator, "G" or microdot "•", may or may not be present.

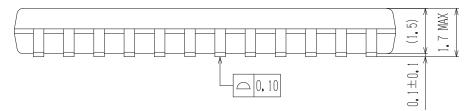
#### Package Dimensions

unit : mm

### [LC72121M]

#### SOIC24 W / MFP24S (300 mil) CASE 751CG ISSUE O





#### **Package Dimensions**

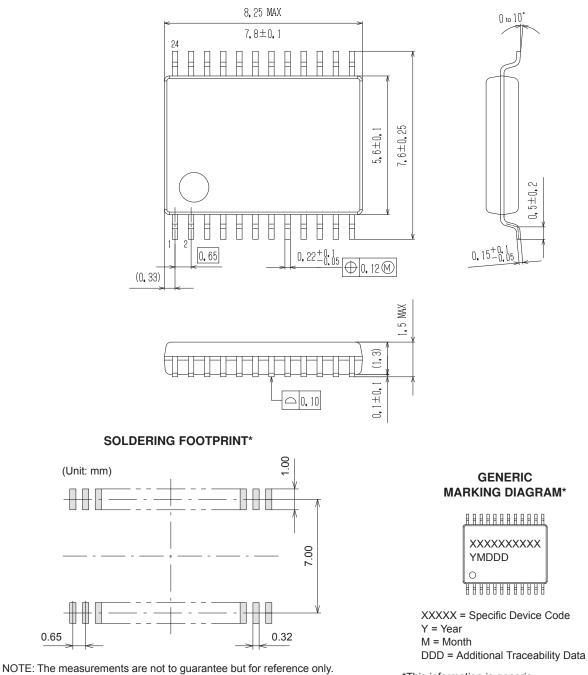
unit : mm

#### [LC72121V]

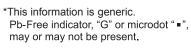
#### SSOP24 (275mil)

0.65

CASE 565AQ ISSUE A



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



#### **ORDERING INFORMATION**

Device	Package	Shipping (Qty / Packing)
LC72121-D-E	DIP22S(300mil) (Pb-Free)	22 / Fan-Fold
LC72121M-TLM-E	MFP24S(300mil) (Pb-Free)	2000 / Tape and Reel
LC72121V-D-MPB-E	SSOP24(275mil) (Pb-Free)	60 / Fan-Fold
LC72121V-D-TML-E	SSOP24(275mil) (Pb-Free)	1000 / Tape and Reel
LC72121V-TLM-E	SSOP24(275mil) (Pb-Free)	1000 / Tape and Reel

† For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. http://www.onsemi.com/pub\_link/Collateral/BRD8011-D.PDF

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